

**Infineon**

## Automotive Power CAD

# Statistical Simulation Methodology for a Smart Power Technology

2007, Oct 19<sup>th</sup>  
AK Bipolar 2007 / Munich

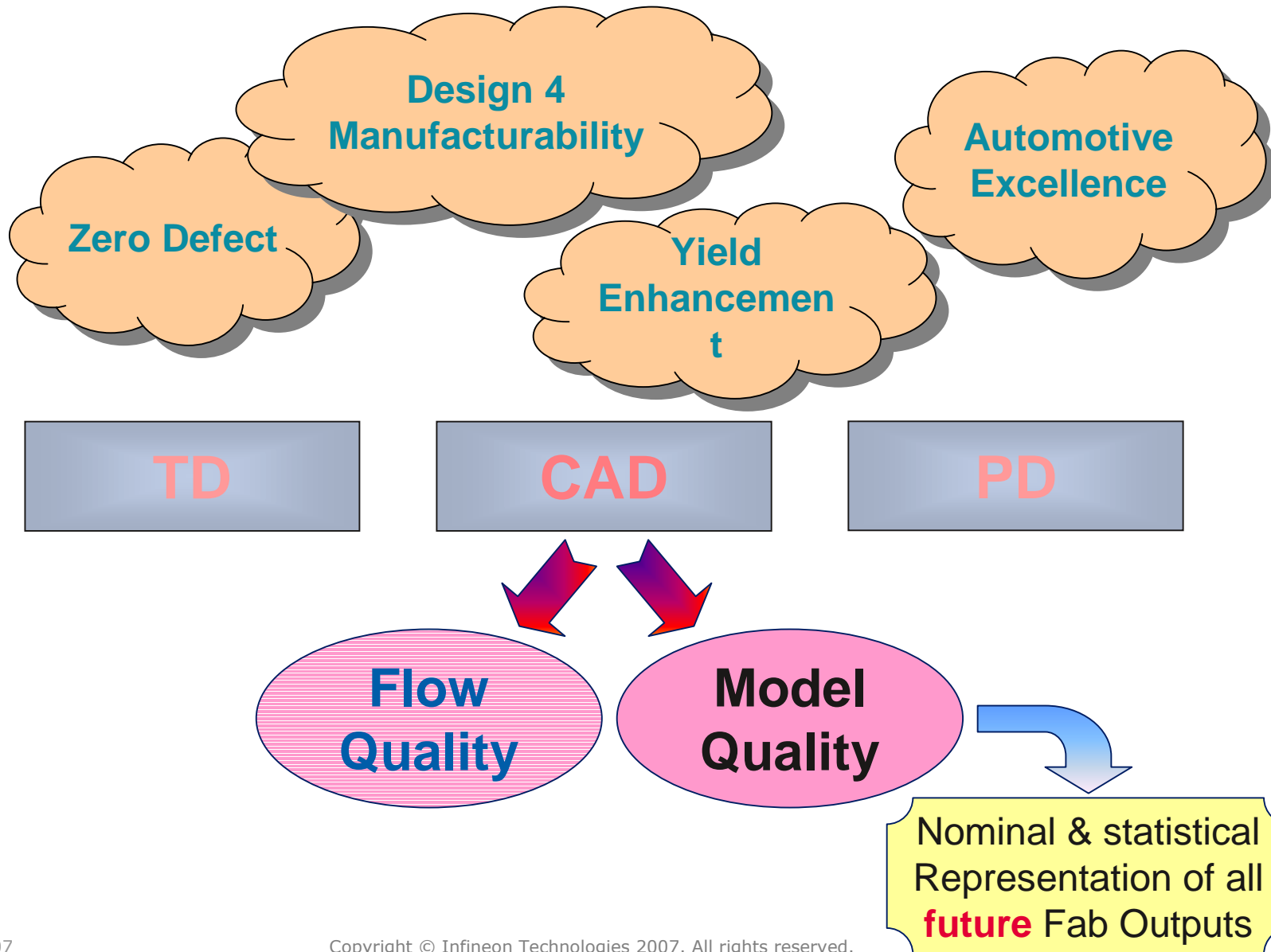
**Dr. Elmar Gondro**



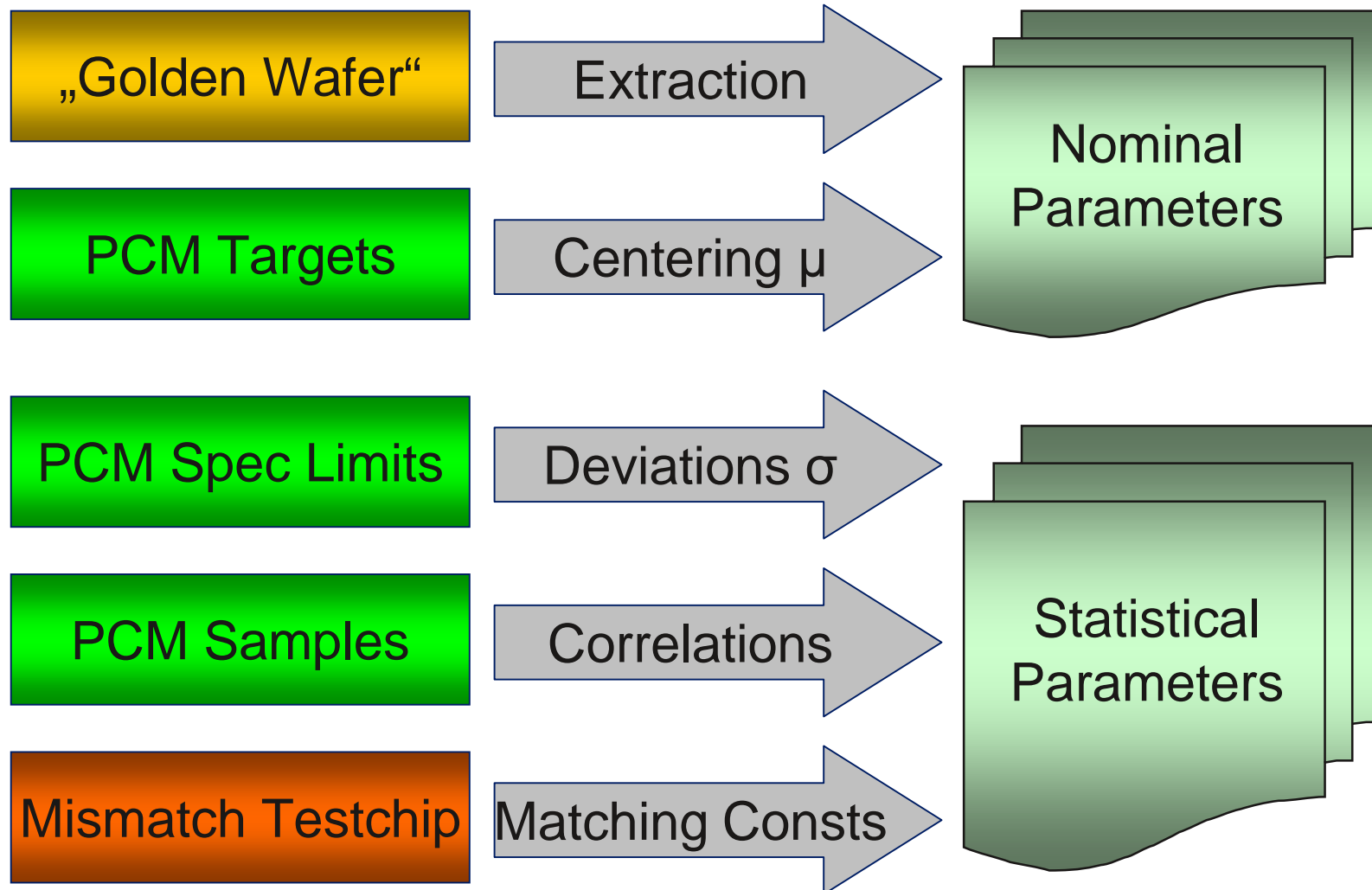
Never stop thinking

- Motivation
- Modeling Flow
- Model Quality
- Conclusion

# Motivation / Wake-Up

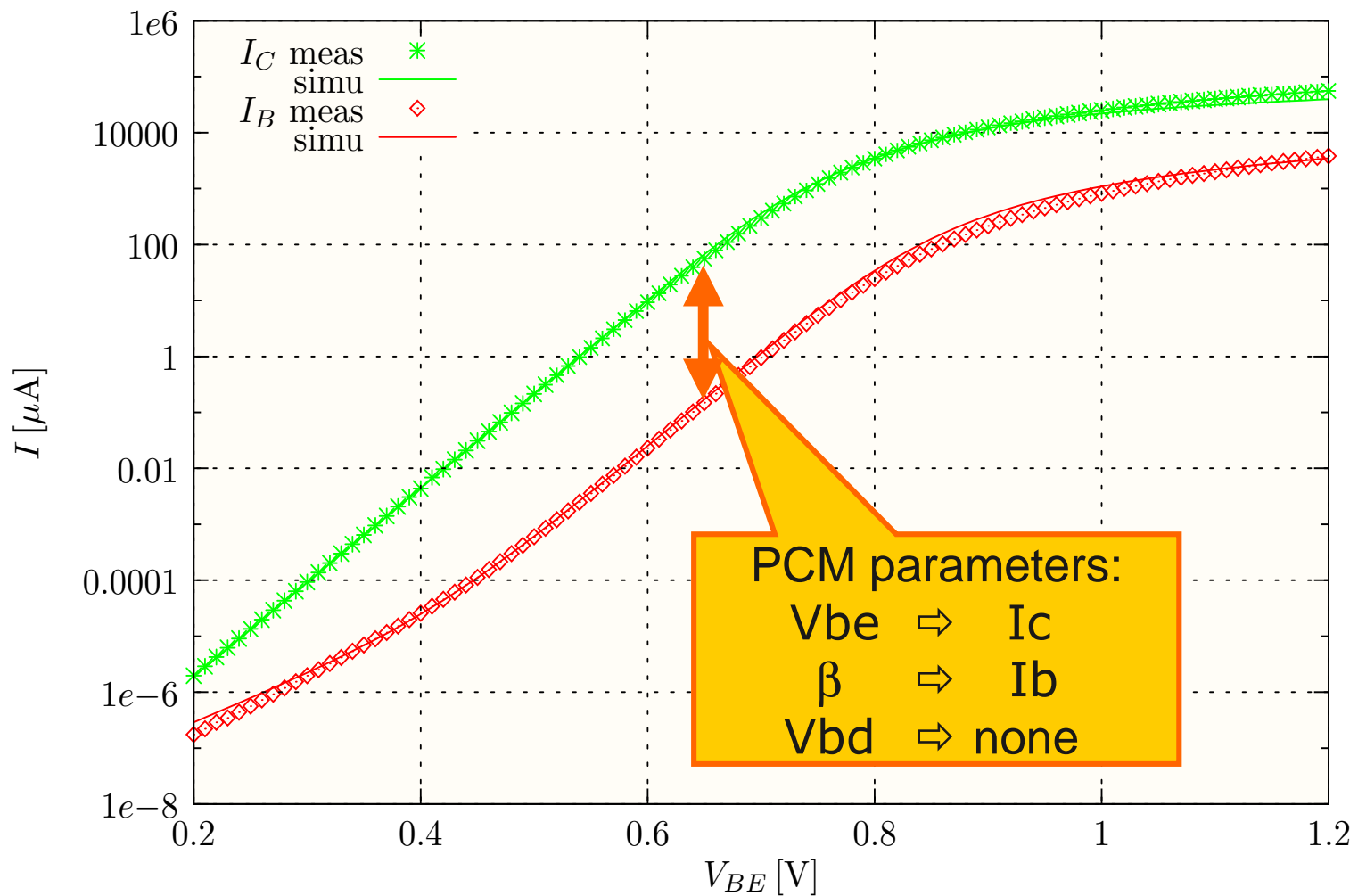


# Five Steps Extraction Process of Electrical Parameters



# Step 1: Nominal Parameters

- „Golden Wafer“
- PCM Targets
- PCM Links
- PCM Samples
- Mismatch



source: **IEP**-Docu (Bipolar / Tempsense)

# Step 1: Nominal Parameters

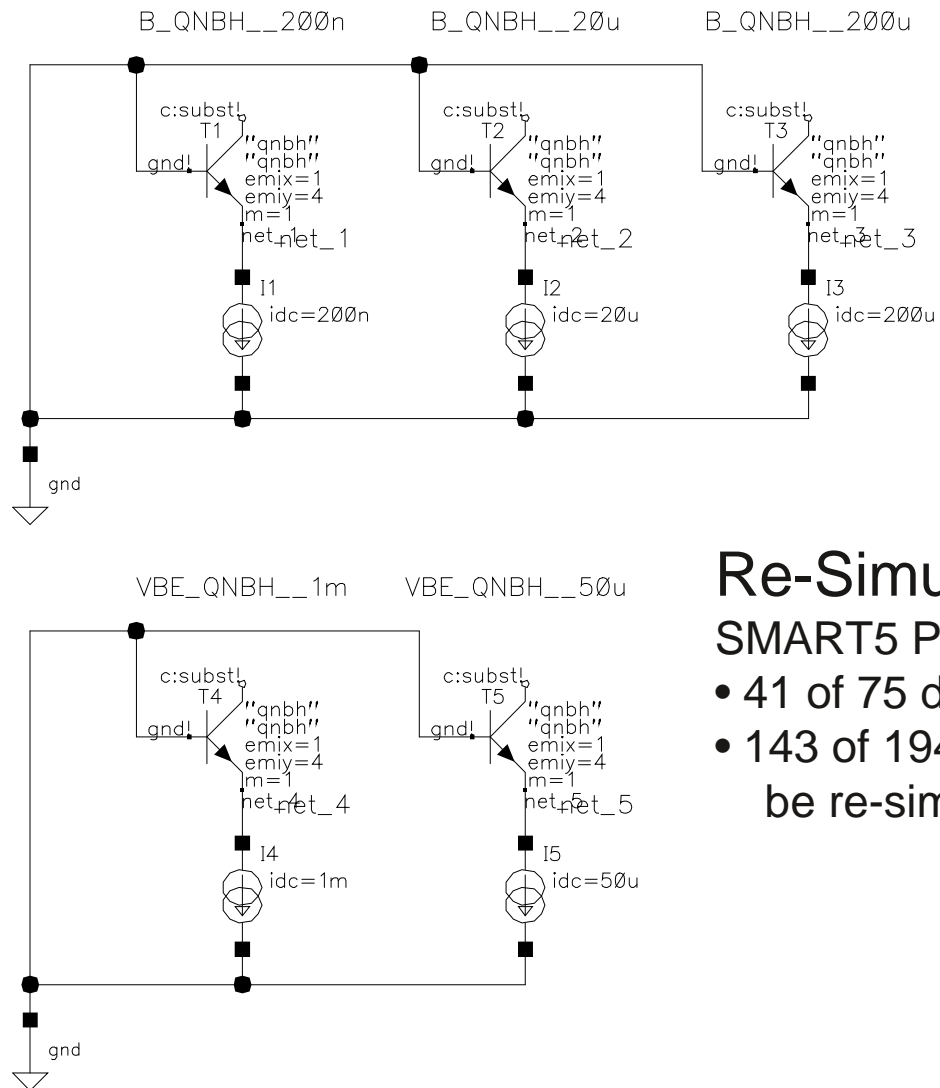
„Golden Wafer“

PCM Targets

PCM Links

PCM Samples

Mismatch



## Re-Simulation Schematics

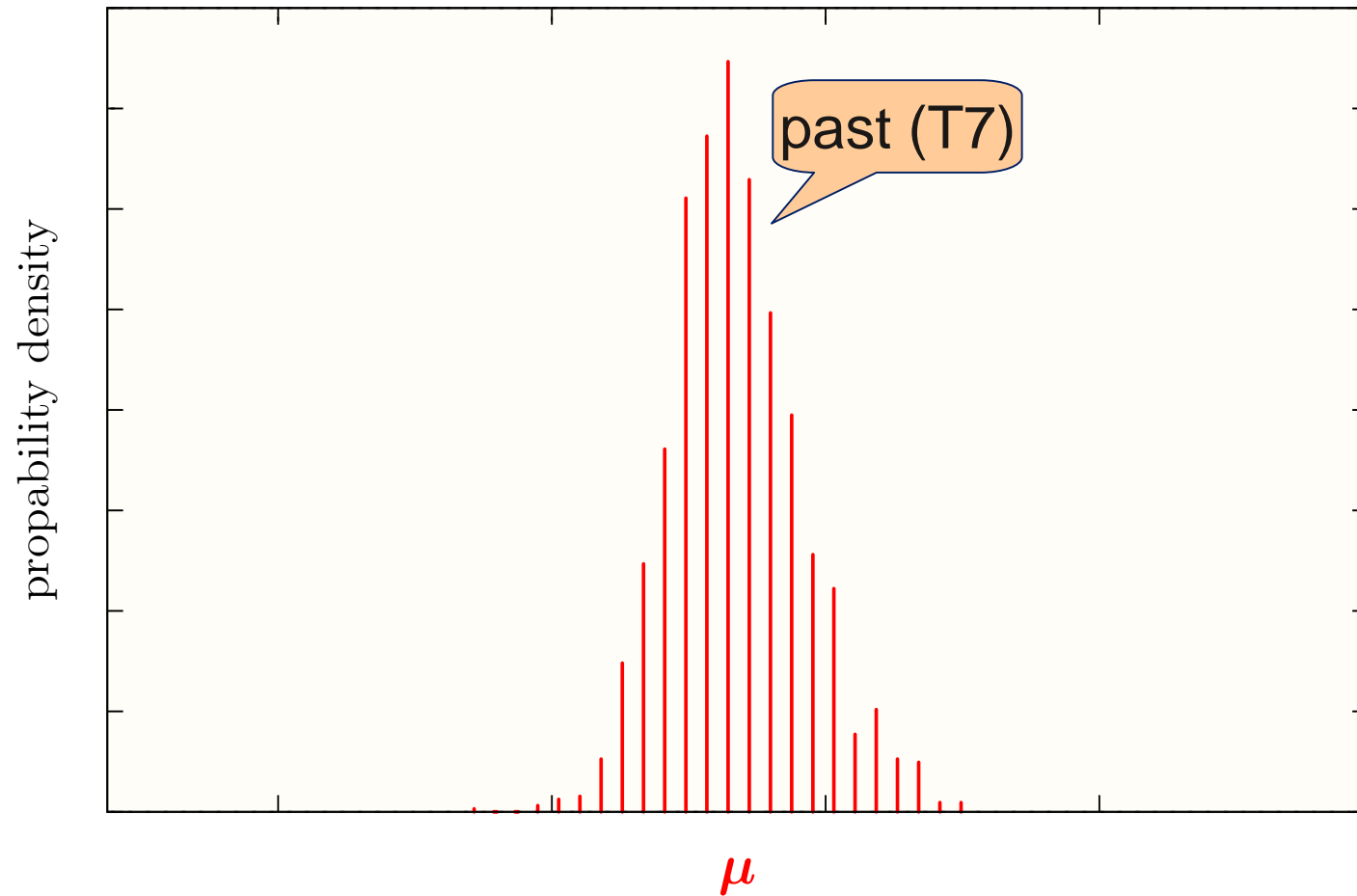
### SMART5 PCM:

- 41 of 75 device types covered
- 143 of 194 PCM setups can be re-simulated simultaneously

source: **/PCM/**-Docu (Bipolar)

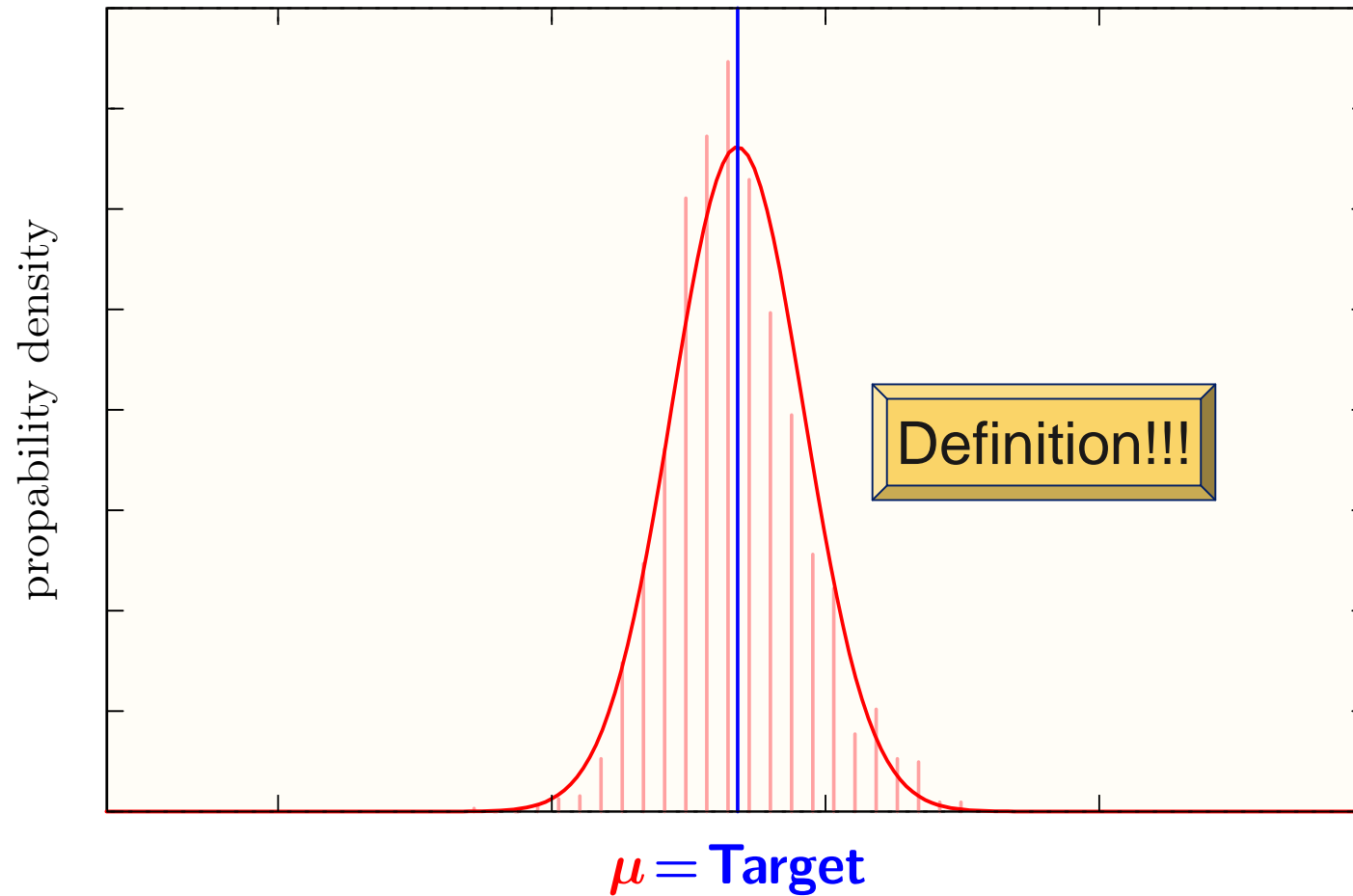
# Step 2: Parameter Centering

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



# Step 2: Parameter Centering

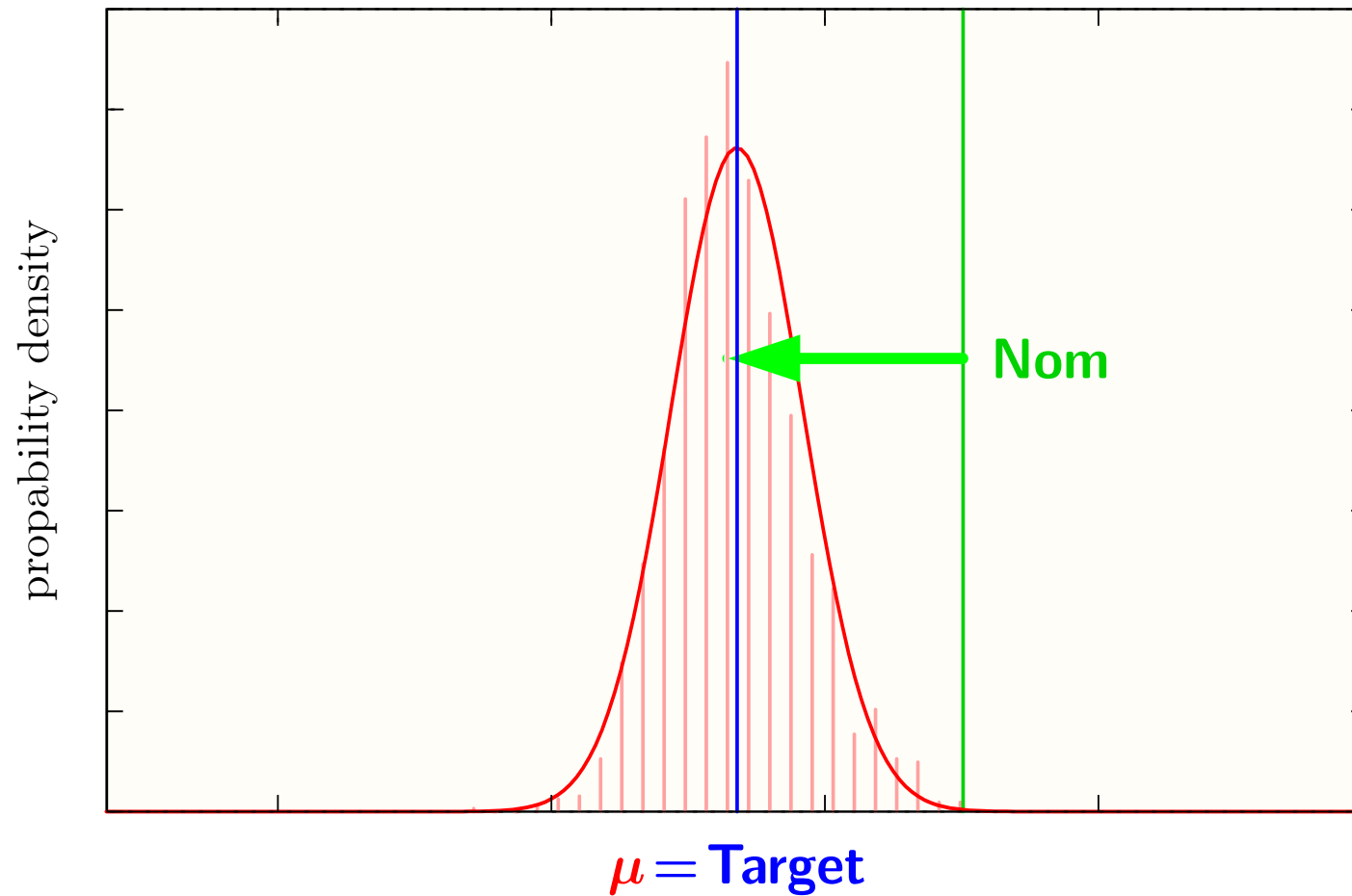
- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch





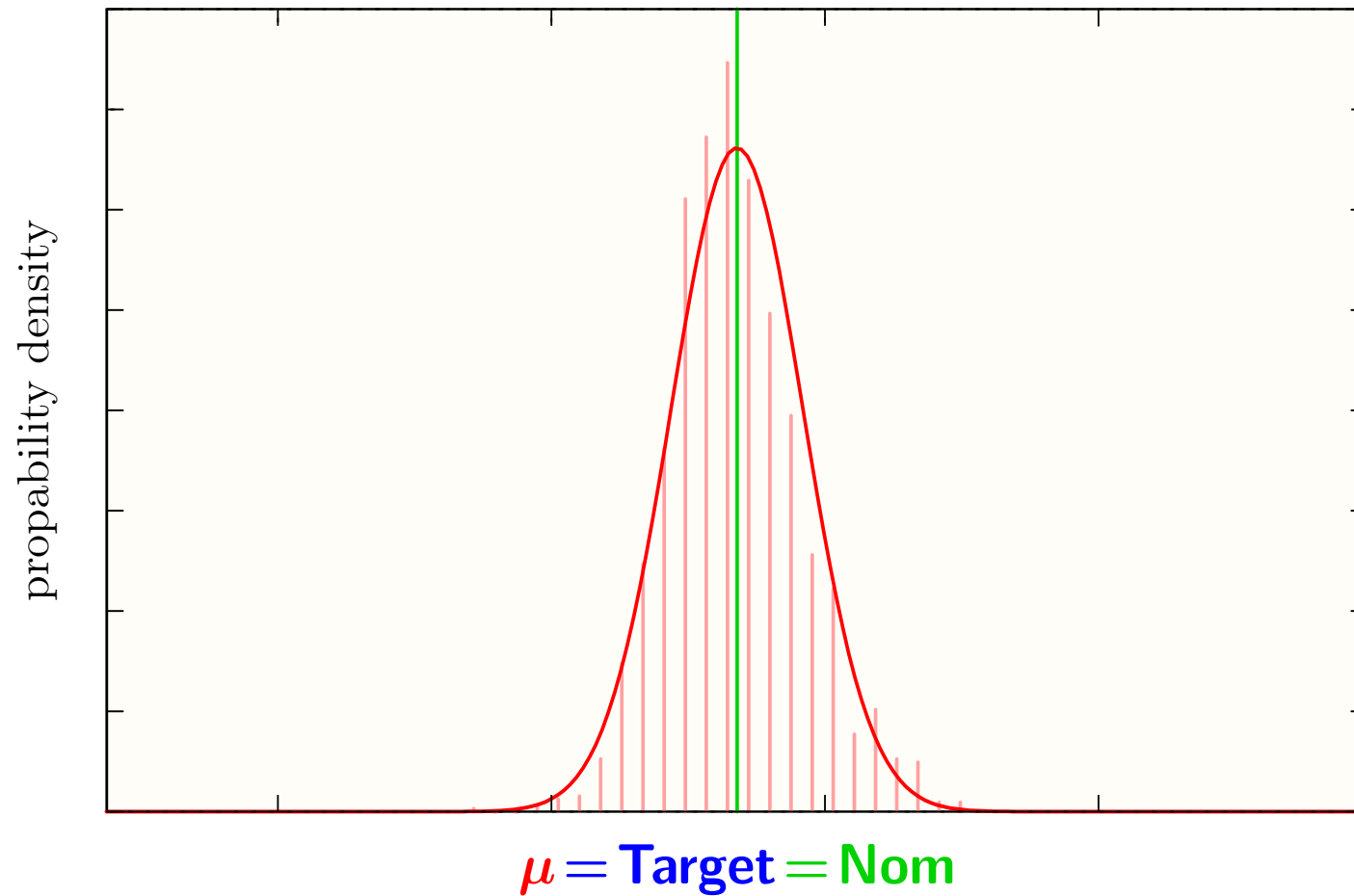
# Step 2: Parameter Centering

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



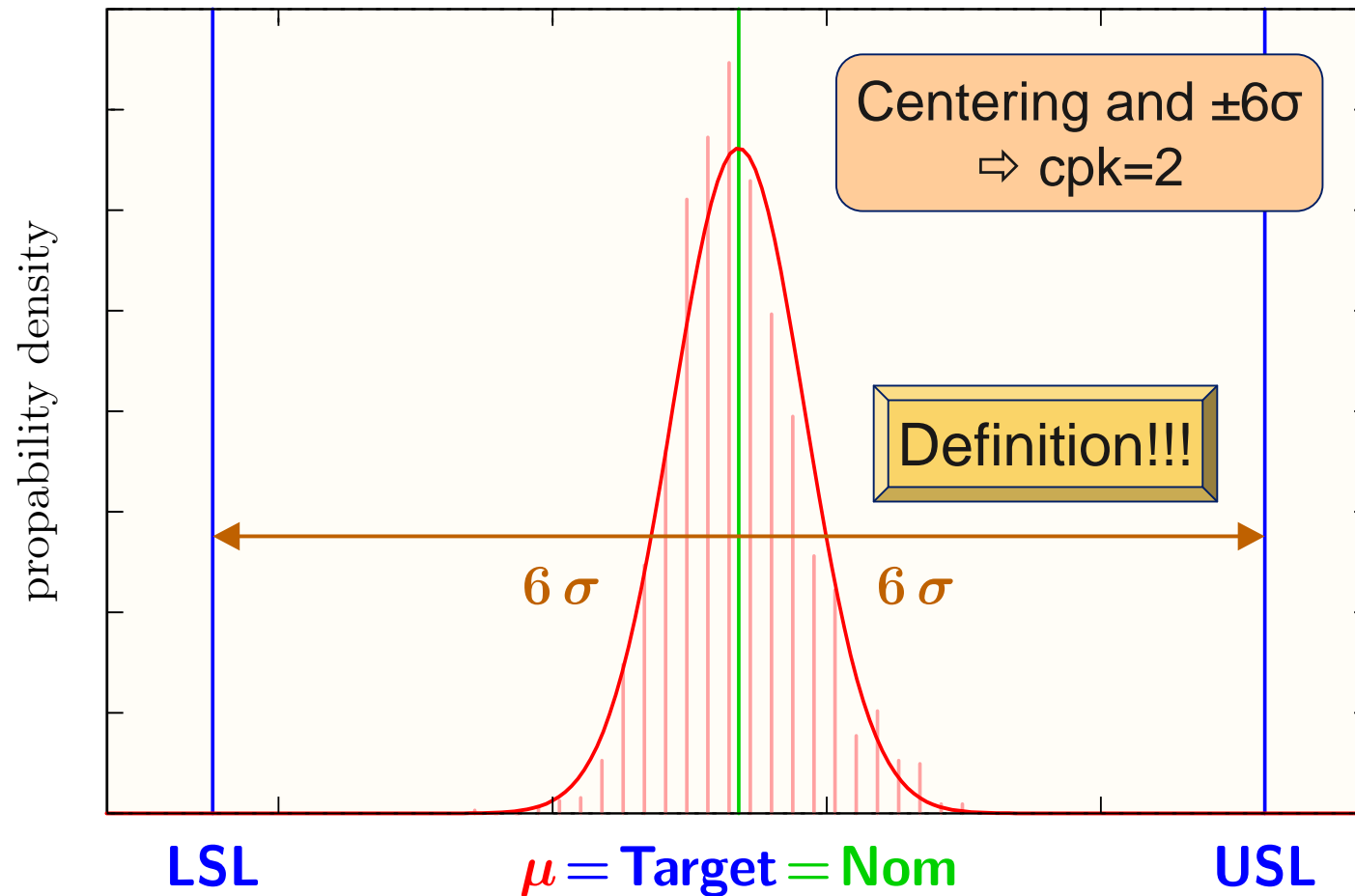
# Step 2: Parameter Centering

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



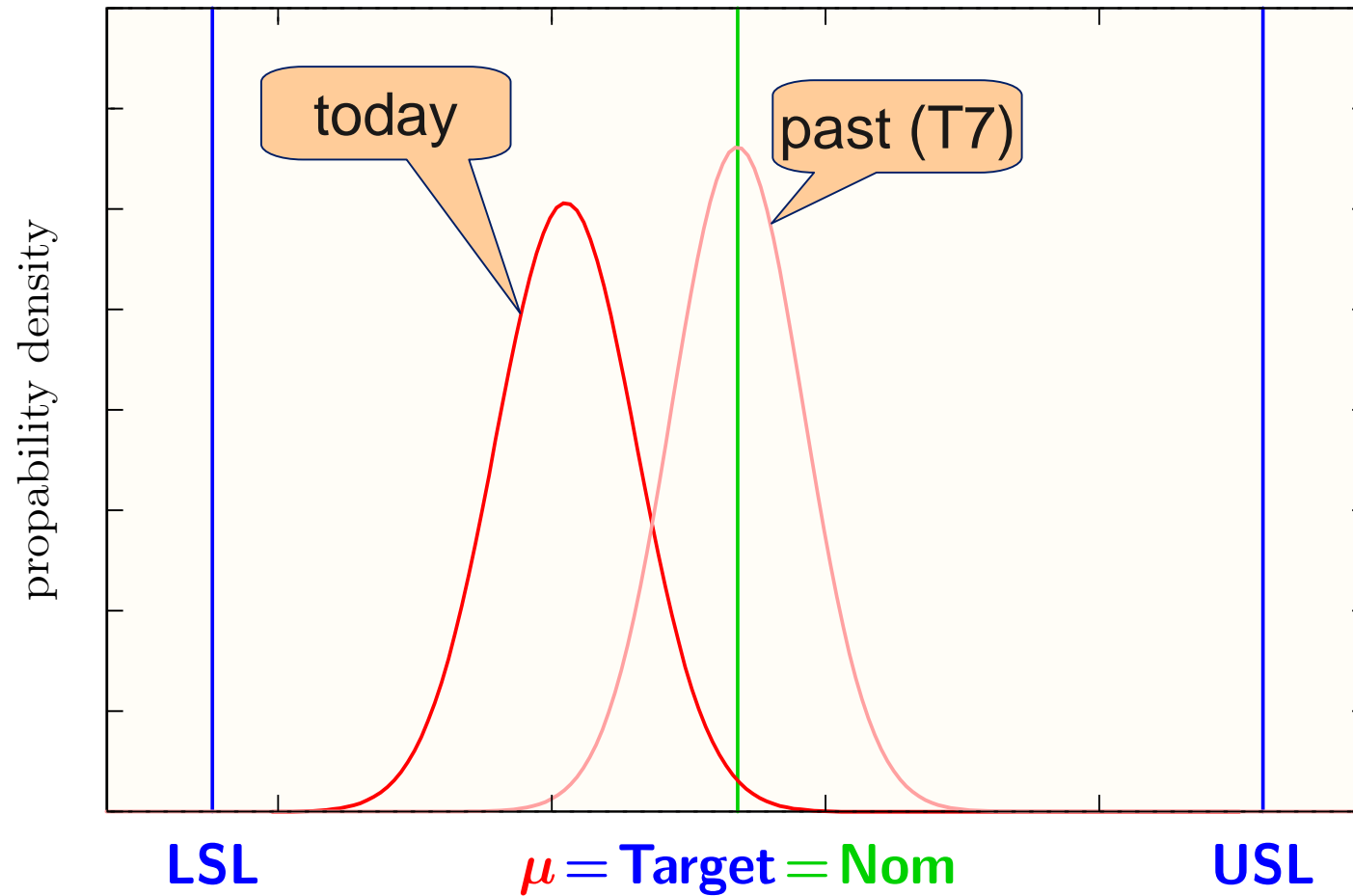
# Step 3: Process Deviations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



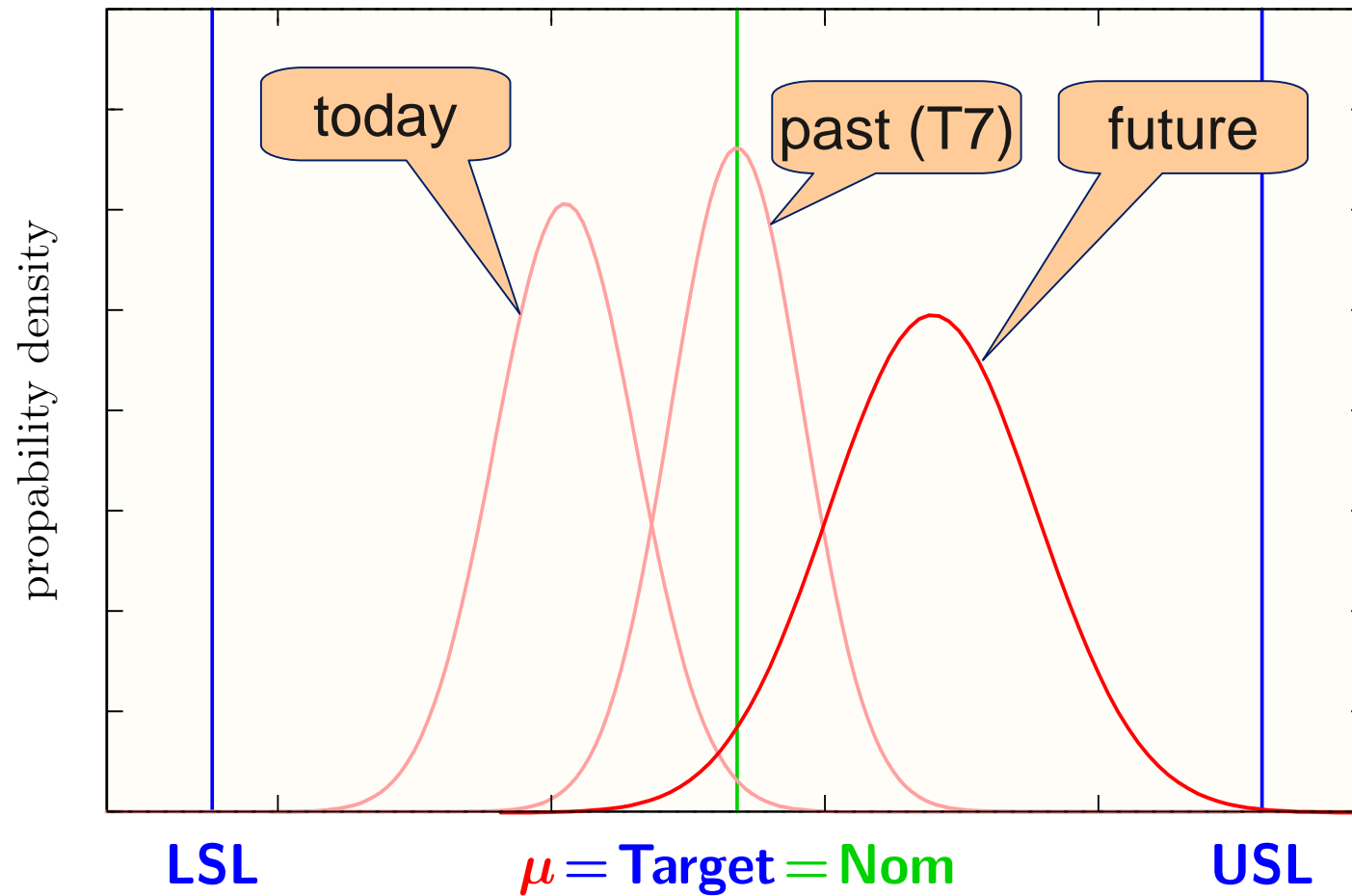
# Step 3: Process Deviations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



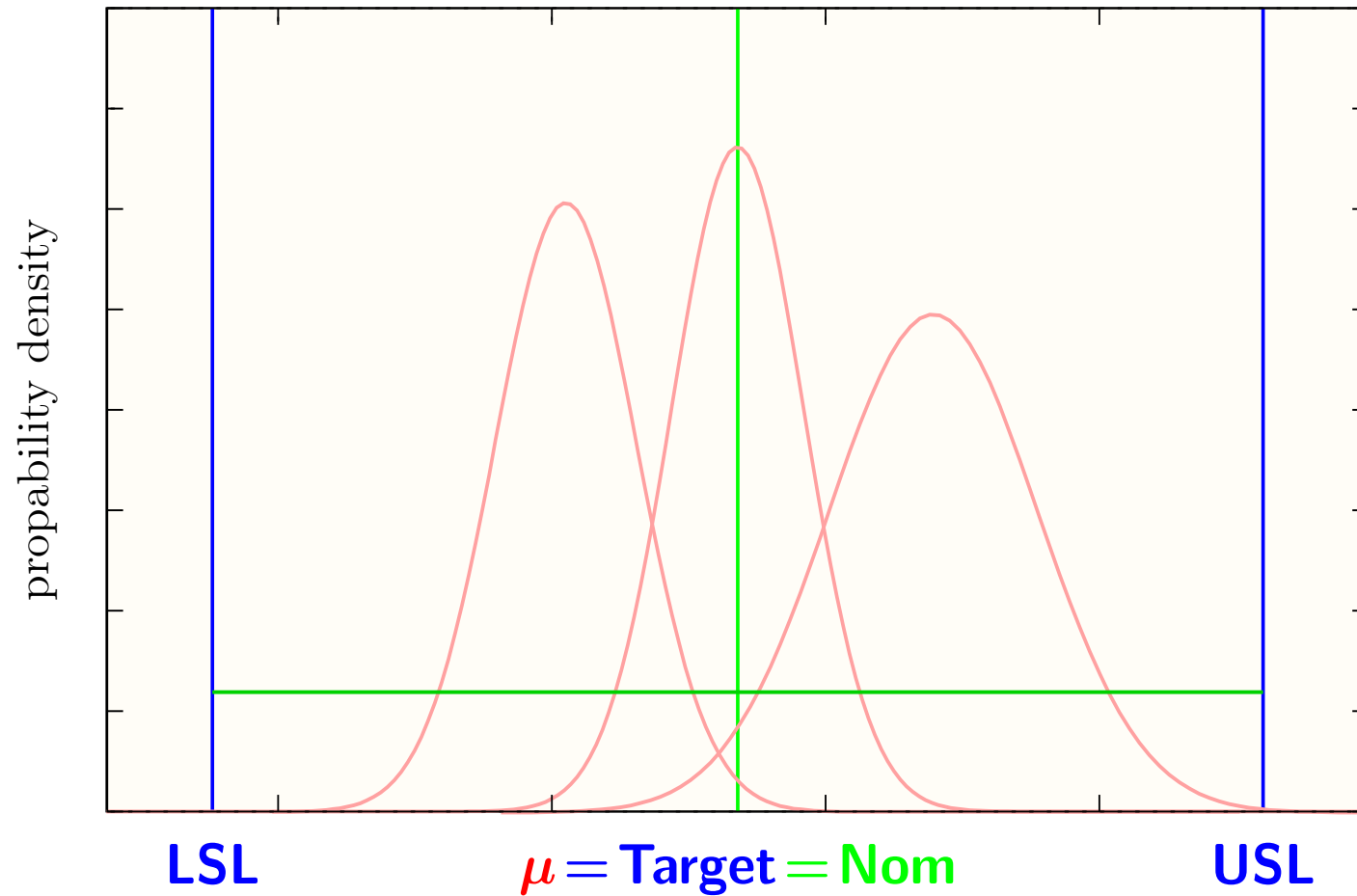
# Step 3: Process Deviations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



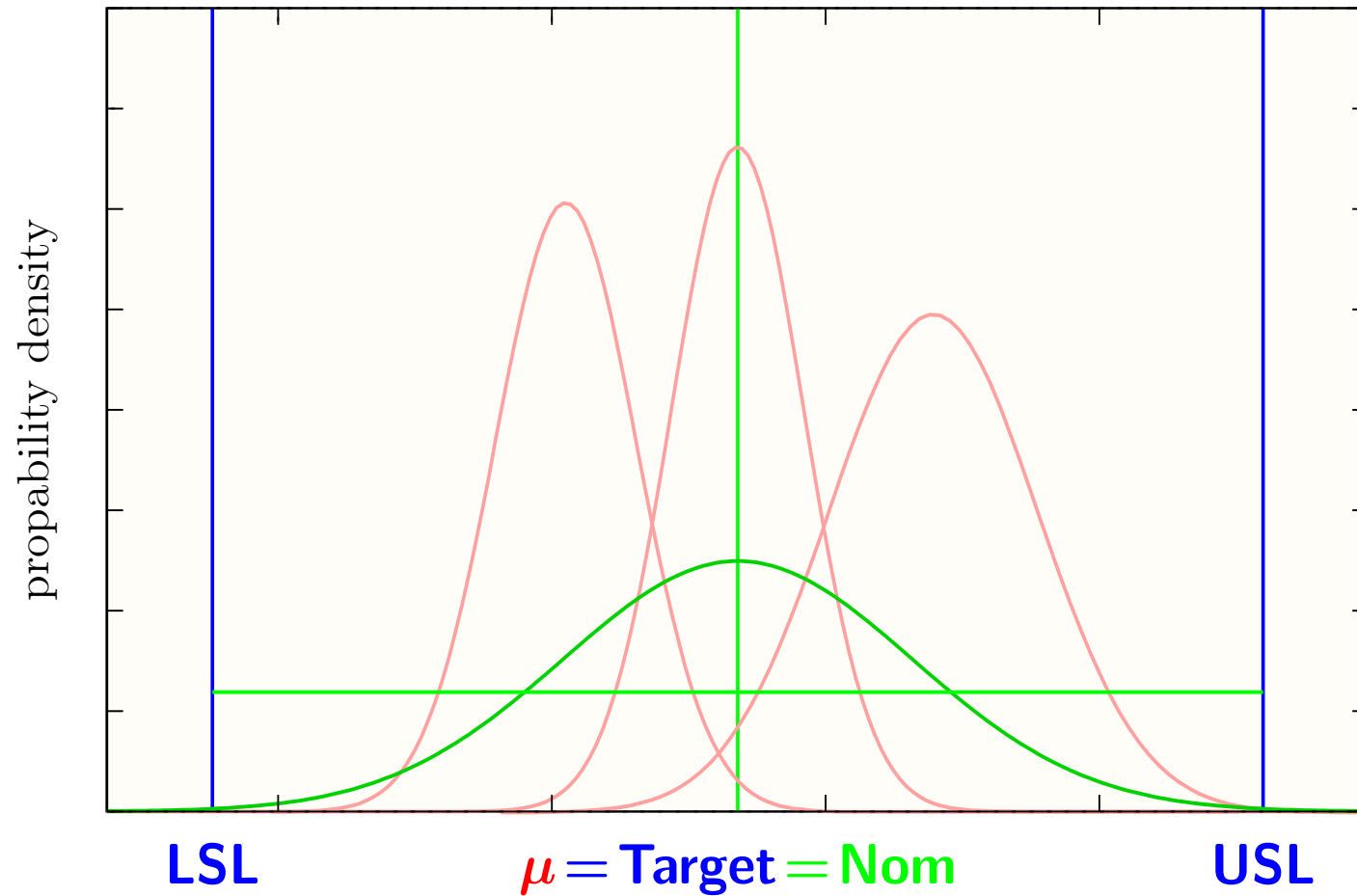
# Step 3: Process Deviations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



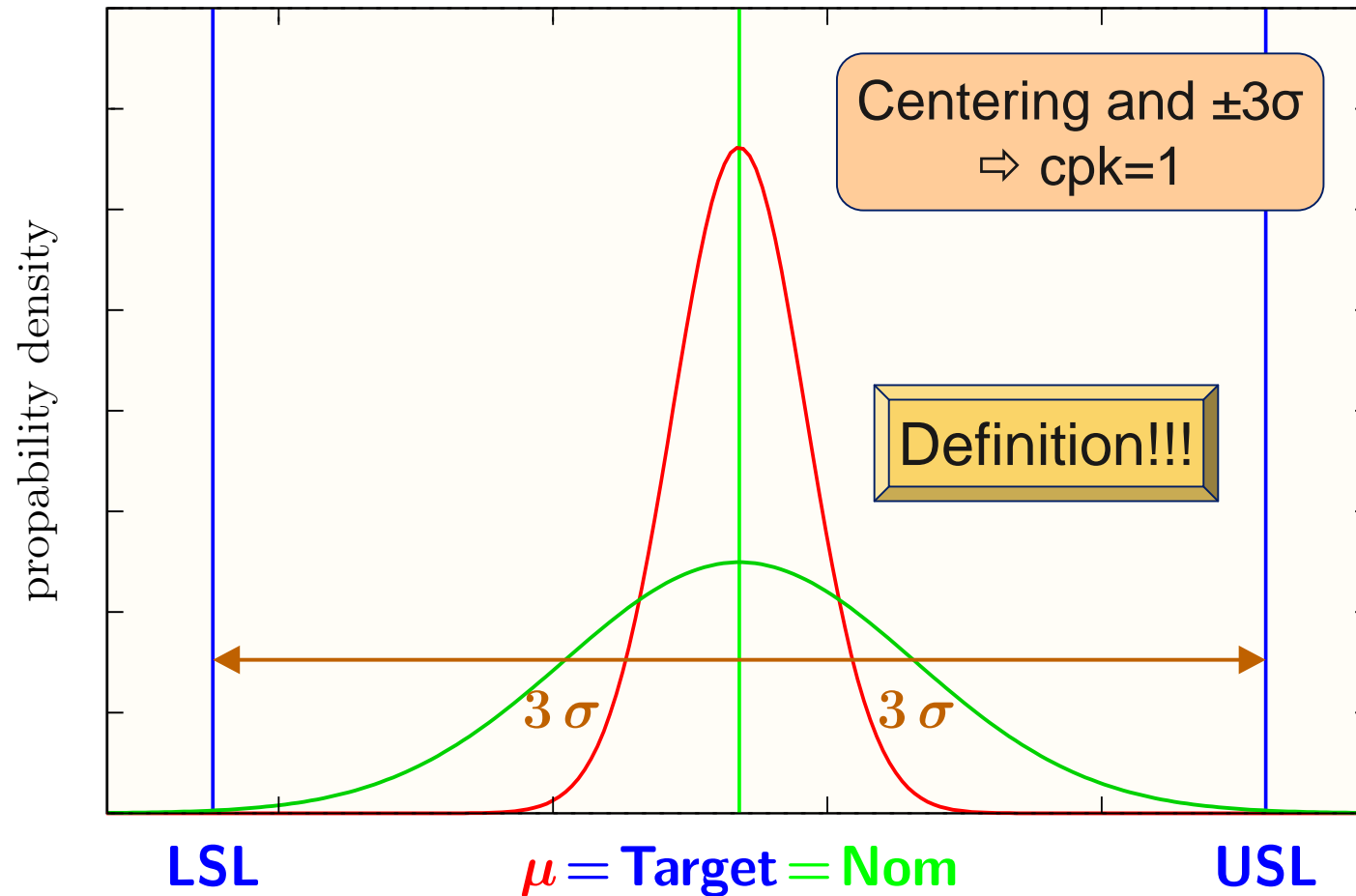
# Step 3: Process Deviations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



# Step 3: Process Deviations

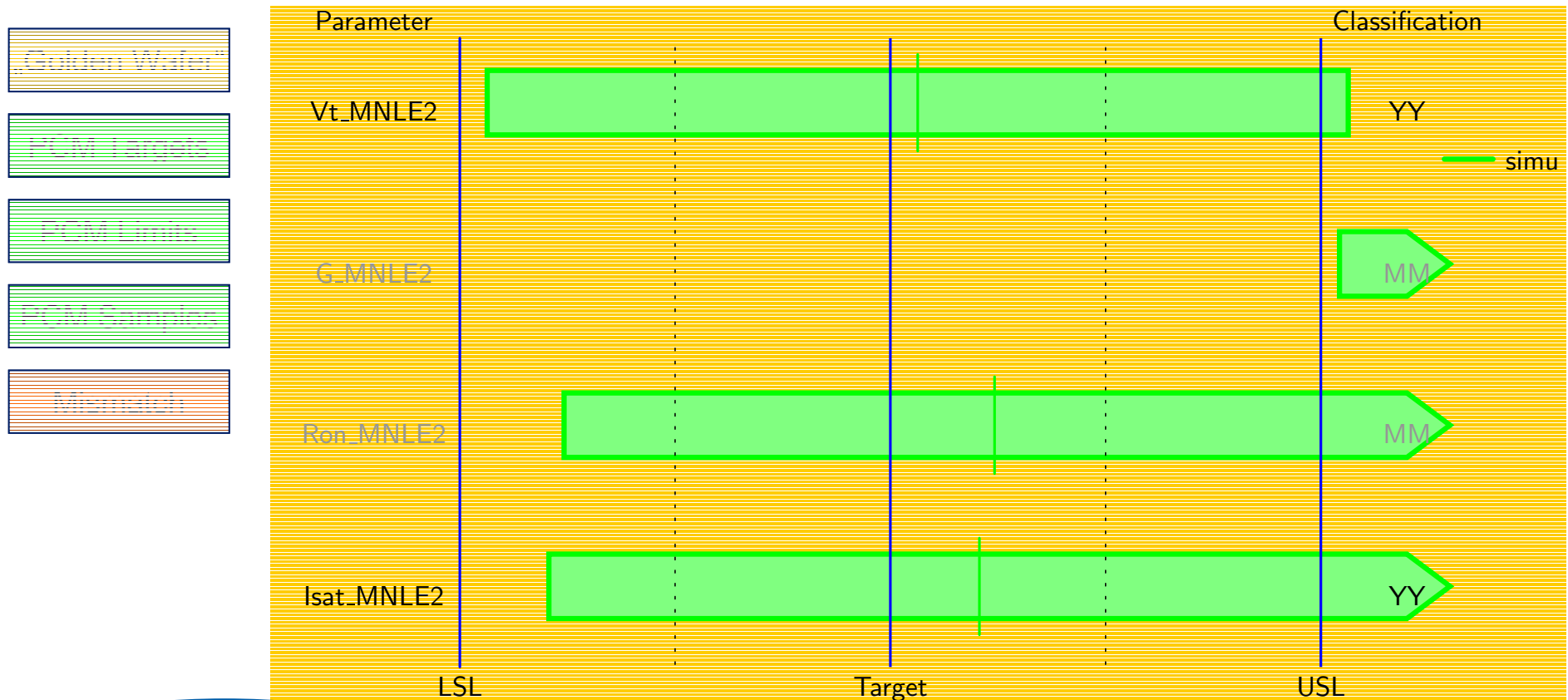
- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch





# Step 3: Process Deviations

## Normalized PCM Window with 3 $\sigma$ Process Variations

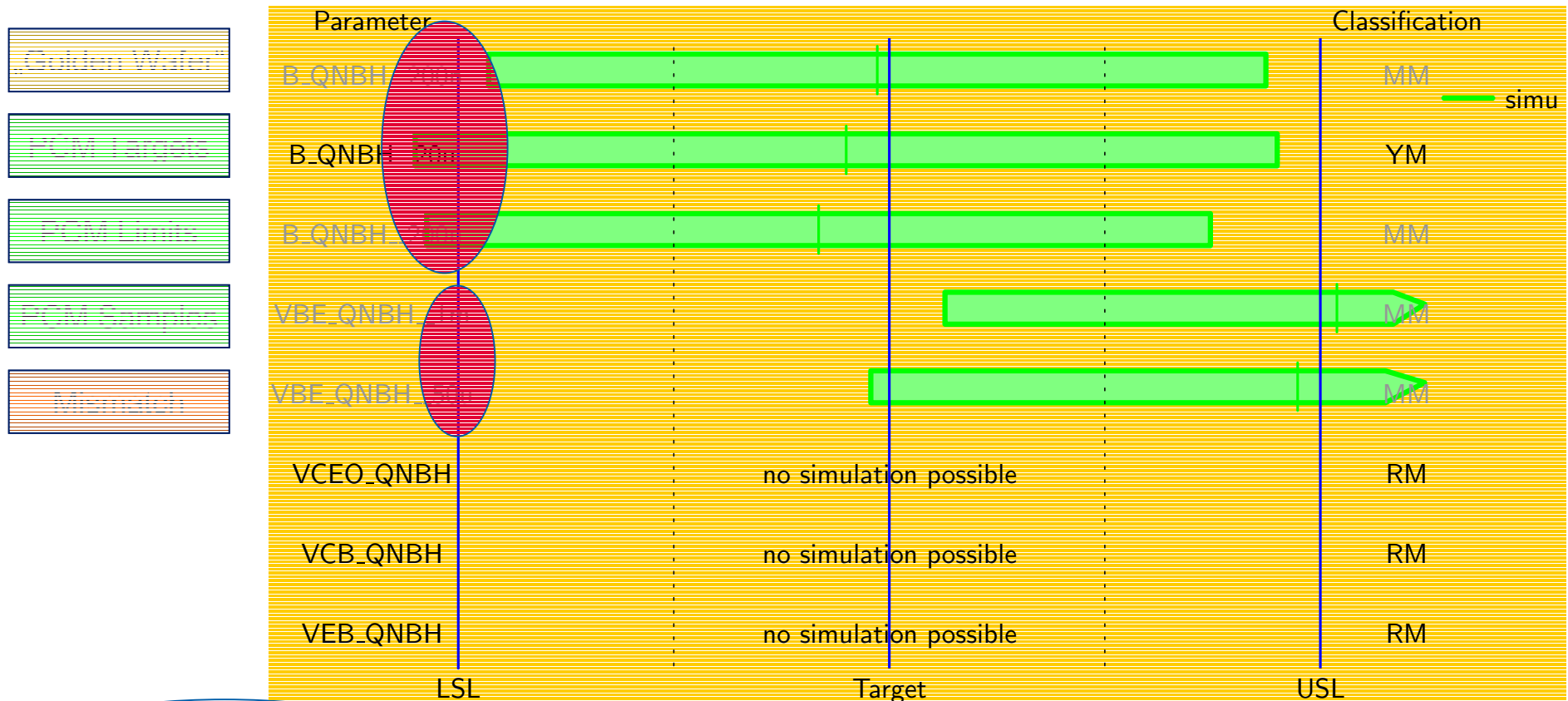


MOSFET

source: /MQ/-Docu (Low Volt NMOS)

# Step 3: Process Deviations

## Normalized PCM Window with 3 $\sigma$ Process Variations



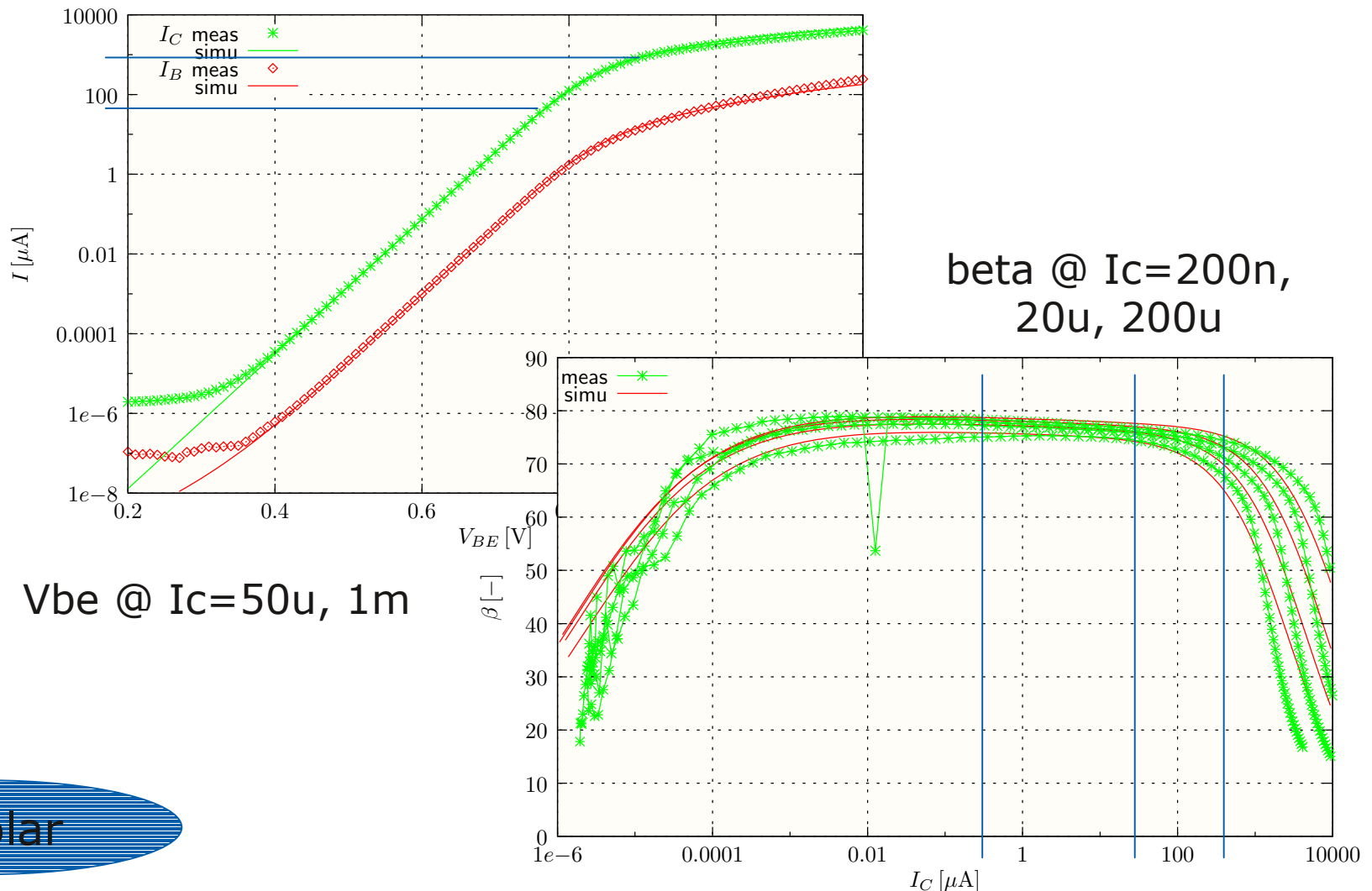
**Bipolar**

source: /MQ/-Docu (qnbh Bipolar)

# Step 3: Process Deviations

## Gummel Poon and beta Plot

- „Golden Wafer“
- PCM Targets
- PCM Lines
- PCM Samples
- Mismatch



**Bipolar**

source: **IEP**-Docu (qnbh Bipolar)

# Step 4: Correlation Table

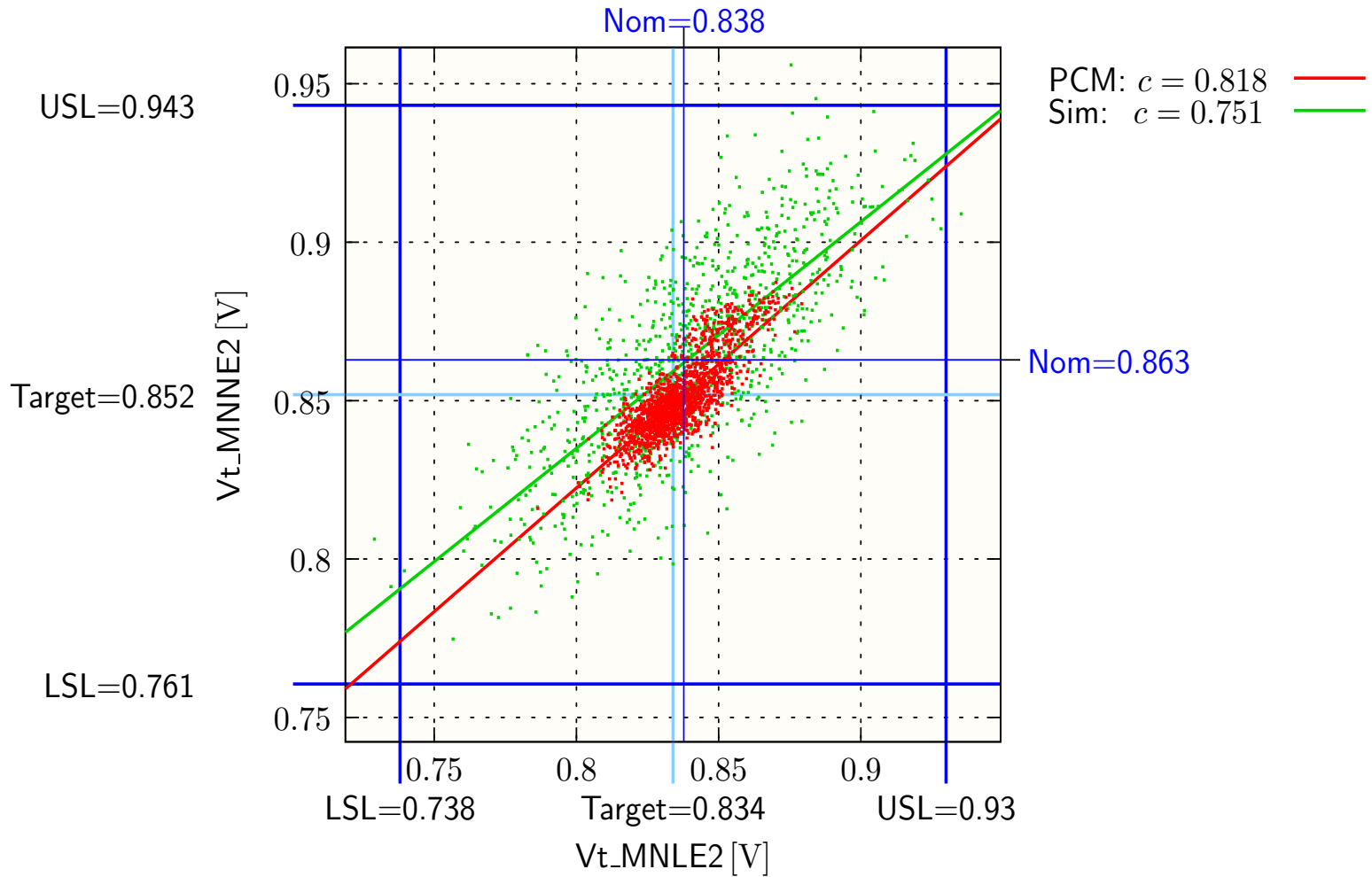


- Golden Wafer
- PCM Targets
- PCM Lines
- PCM Samples
- Mismatch

		mnle	mnle2	mnle2n	mpne	mpne2	mnnd	mnnd2	mnme2	mnhe2	mnhd	mnhd2	mple	mpneh	mpne2h	mpnel	mpne2l	mphe	mphe2	mnte	mnse2	dz6r	dz6s	dz8r	
[%]	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	vth0	bv	bv	bv	
mnle	vth0	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnle2	vth0	68	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnle2n	vth0	59	61	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mpne	vth0	53	70	68	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mpne2	vth0	61	73	72	59	67	69	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnnd	vth0						94	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnnd2	vth0							90	91	-	100	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnme2	vth0								77	78	-	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnhe2	vth0									82	-	100	100	100	100	100	100	100	100	100	100	100	100	100	
mnhd	vth0										21	-	100	100	100	100	100	100	100	100	100	100	100	100	
mnhd2	vth0											60	-	100	100	100	100	100	100	100	100	100	100	100	
mple	vth0												60	-	100	100	100	100	100	100	100	100	100	100	
mpneh	vth0													60	-	100	100	100	100	100	100	100	100	100	
mpne2h	vth0														32	43	-	100	100	100	100	100	100	100	
mpnel	vth0															64	85	42	-	100	100	100	100	100	
mpne2l	vth0																34	42	81	43	-	100	100	100	
mphe	vth0																	47	66	21	65	20	-	100	
mphe2	vth0																		31	41	78	41	78	29	-
mnte	vth0																			20	18	33	25	-	100
mnse2	vth0																				36	39	46	46	-
dz6r	bv																							92	-
dz6s	bv																								92
dz8r	bv																								-

# Step 4: Correlations

- „Golden Wafer“
- PCM Targets
- PCM Limits
- PCM Samples
- Mismatch



source: /PCM/-Docu

# Step 5: Mismatch Parameters

„Golden Wafer“

PCM Targets

PCM Limits

PCM Samples

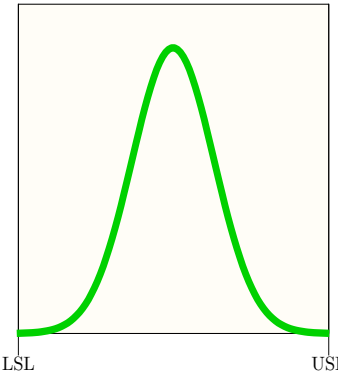
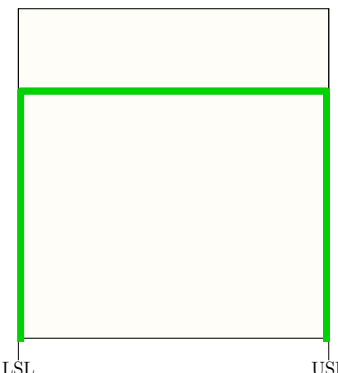
Mismatch

Special Device Pair Measurements on Testchip required

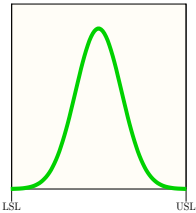
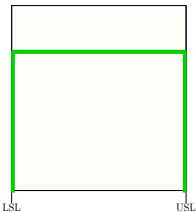
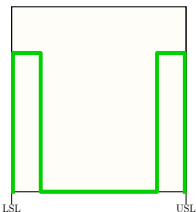
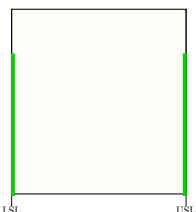
$$\sigma_{mismatch} = \frac{const_{mismatch}}{\sqrt{2 Area}}$$

- Threshold voltages of MOS transistors
- Current gains of bipolar
- Sheet resistances of poly resistors

# Monte Carlo Sections

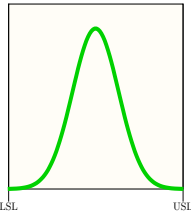
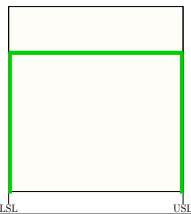
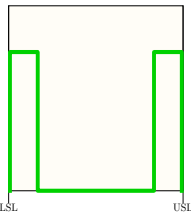
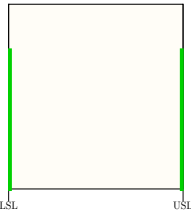
	<i>Comment</i>	<i>Distribution</i>
<b>nom</b>	Gaussian distribution of samples $\mu = \text{Target} = (USL+LSL)/2$ $\sigma = (USL-\mu)/3 = (USL-LSL)/6$	
<b>unif</b>	uniform distribution of samples $\mu = \text{Target} = (USL+LSL)/2$ $\sigma = (USL-\mu)/\text{sqrt}(3) = \sigma[\text{nom}]*\text{sqrt}(3)$	

# Monte Carlo Sections

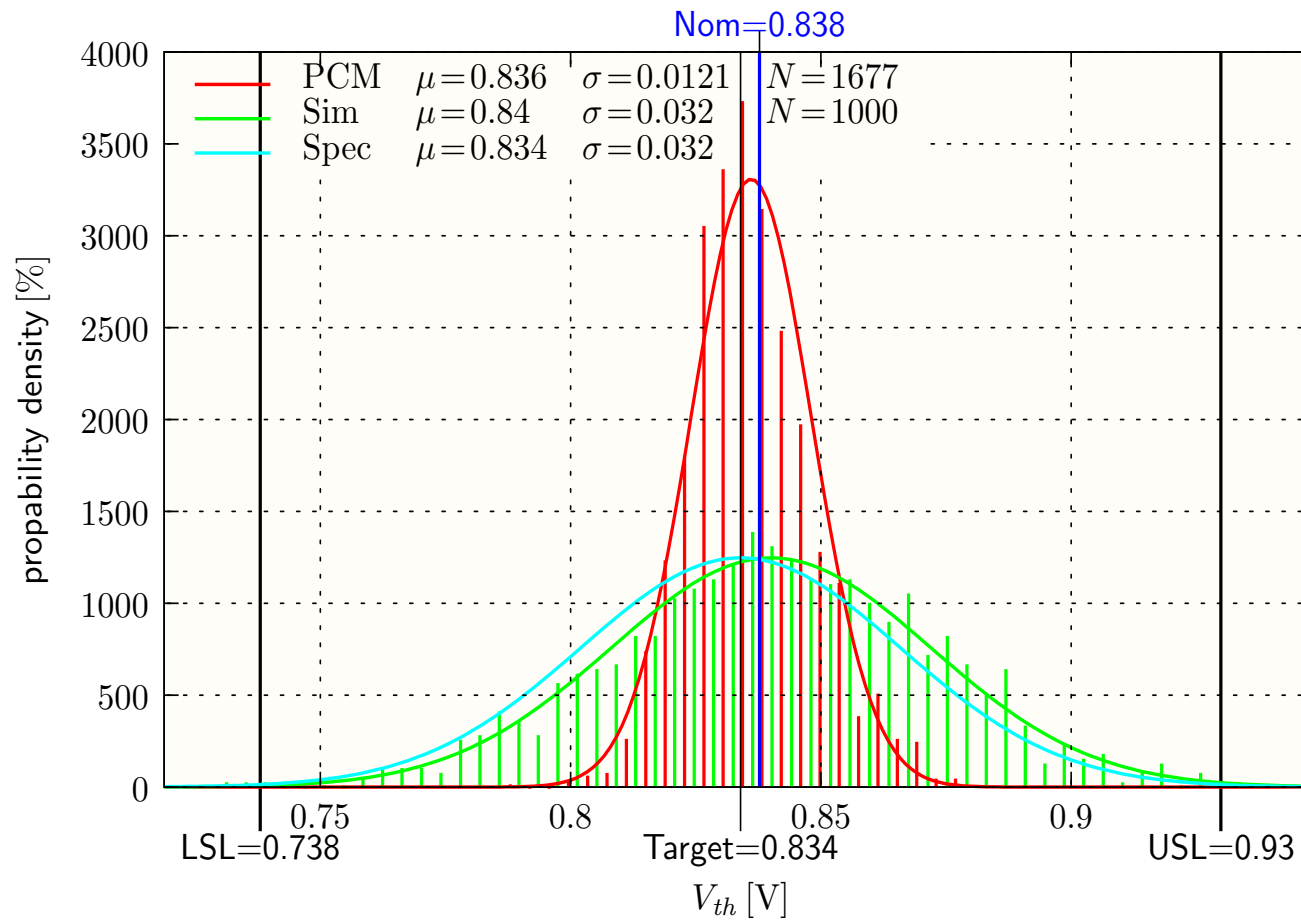
	<b>Comment</b>	<b>Distribution</b>
<b>nom</b>	Gaussian distribution of samples $\mu = Target = (USL+LSL)/2$ $\sigma = (USL-\mu)/3$ $= (USL-LSL)/6$	
<b>unif</b>	uniform distribution of samples $\mu = Target = (USL+LSL)/2$ $\sigma = (USL-\mu)/\sqrt{3}$ $= \sigma[nom]*\sqrt{3}$	
<b>unif2s3s</b>	uniform distribution of samples within 2σ and 3σ $\mu = Target = (USL+LSL)/2$ $\sigma \approx (USL-\mu)*0.84$ $= \sigma[nom]*2.5$	
<b>specLimits</b>	parameters shifted to their Spec Limits (USL or LSL) $\mu = Target = (USL+LSL)/2$ $\sigma = USL-\mu$ $= \sigma[nom]*3$	



# Monte Carlo Sections

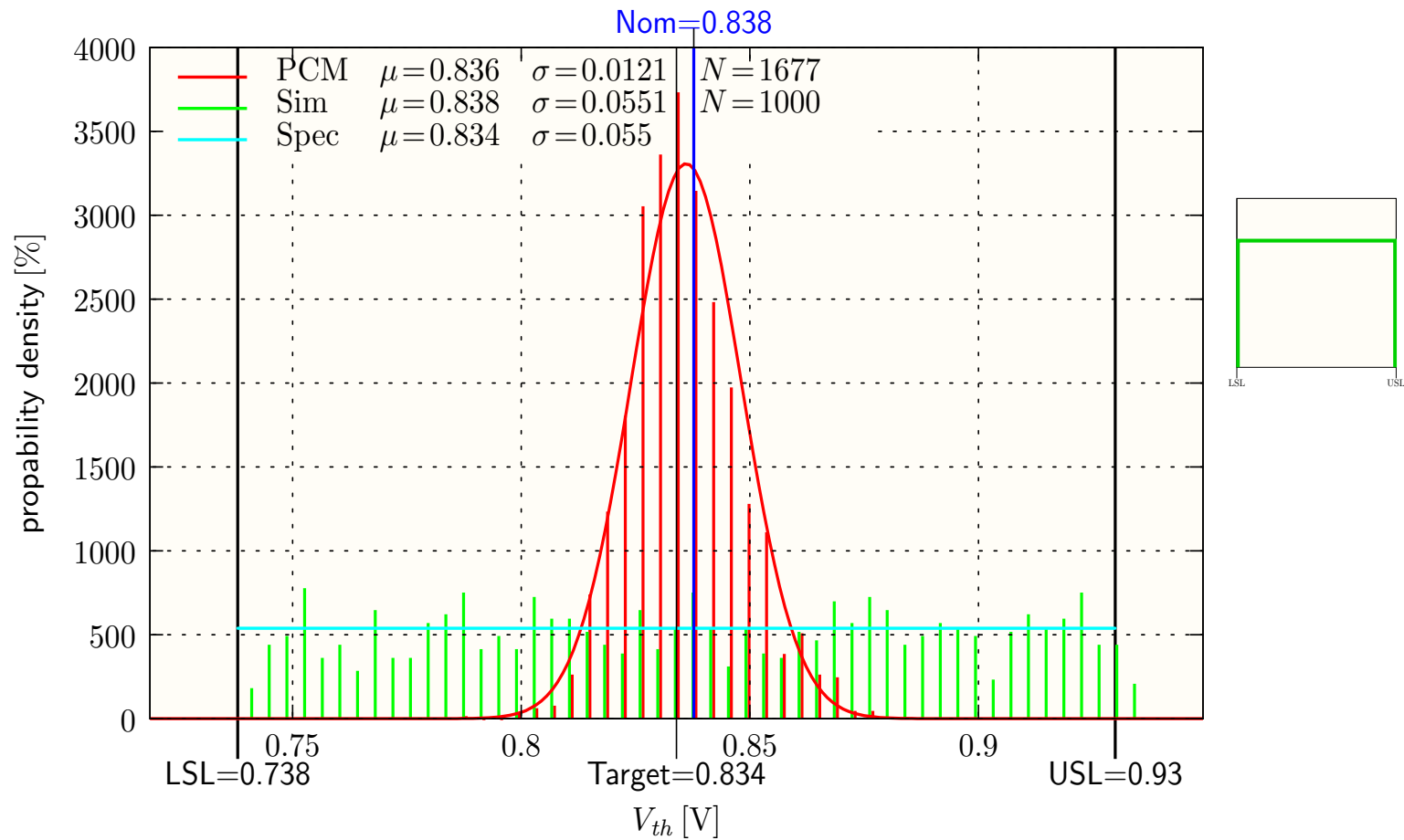
<i>w/ Parasitics</i>	<i>w/o Parasitics</i>	<i>Comment</i>	<i>Distribution</i>
<b>nom</b>	<b>nom_noPar</b>	Gaussian distribution of samples $\mu = Target = (USL+LSL)/2$ $\sigma = (USL-\mu)/3$ $= (USL-LSL)/6$	
<b>unif</b>	<b>unif_noPar</b>	uniform distribution of samples $\mu = Target = (USL+LSL)/2$ $\sigma = (USL-\mu)/\sqrt{3}$ $= \sigma[nom]*\sqrt{3}$	
<b>unif2s3s</b>	<b>unif2s3s_noPar</b>	uniform distribution of samples within 2σ and 3σ $\mu = Target = (USL+LSL)/2$ $\sigma \approx (USL-\mu)*0.84$ $= \sigma[nom]*2.5$	
<b>specLimits</b>	<b>specLimits_noPar</b>	parameters shifted to their Spec Limits (USL or LSL) $\mu = Target = (USL+LSL)/2$ $\sigma = USL-\mu$ $= \sigma[nom]*3$	

# Example 1: PCM Par $V_{t\_MNLE2}$ – MC Section *nom*

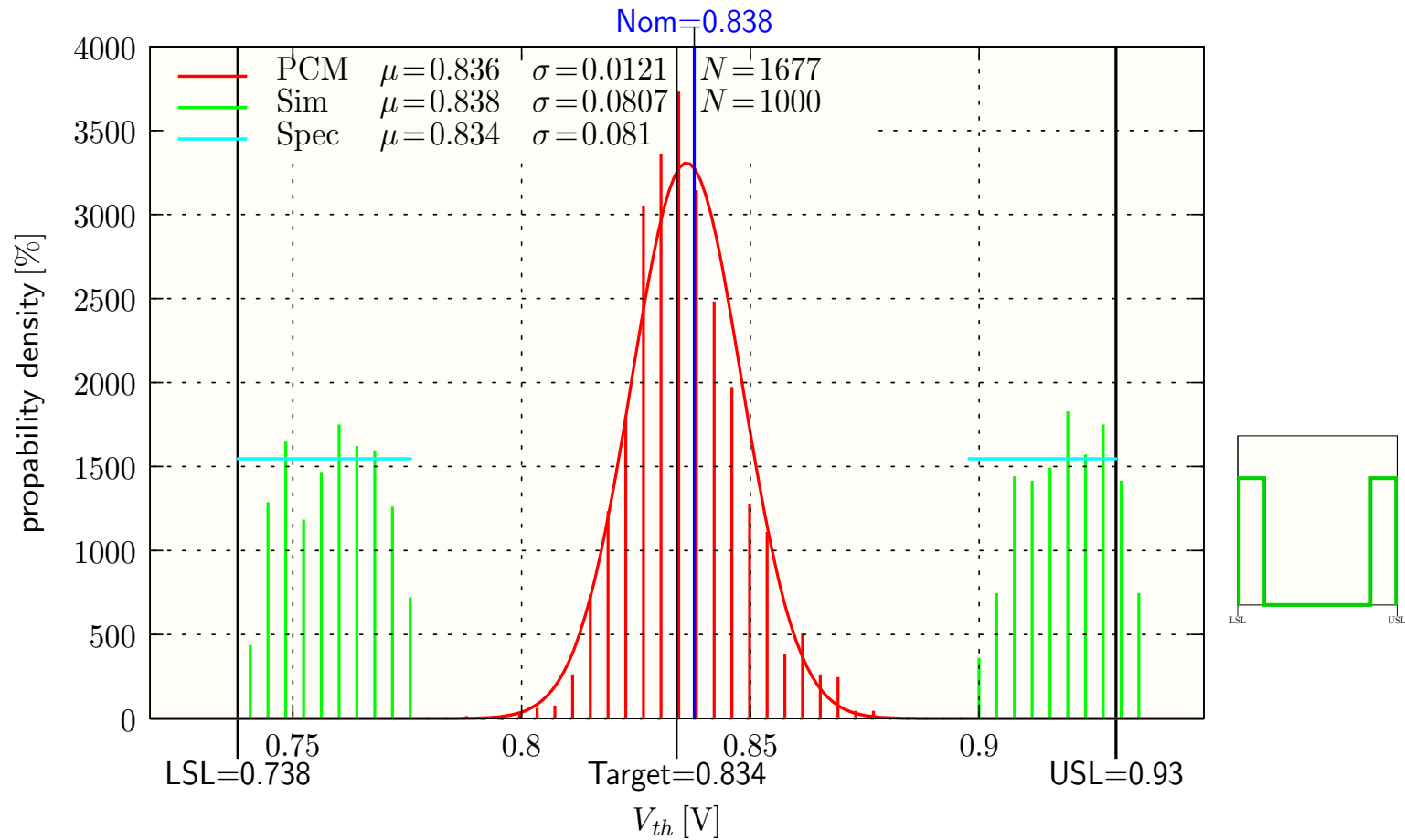


source: /PCM/-Docu

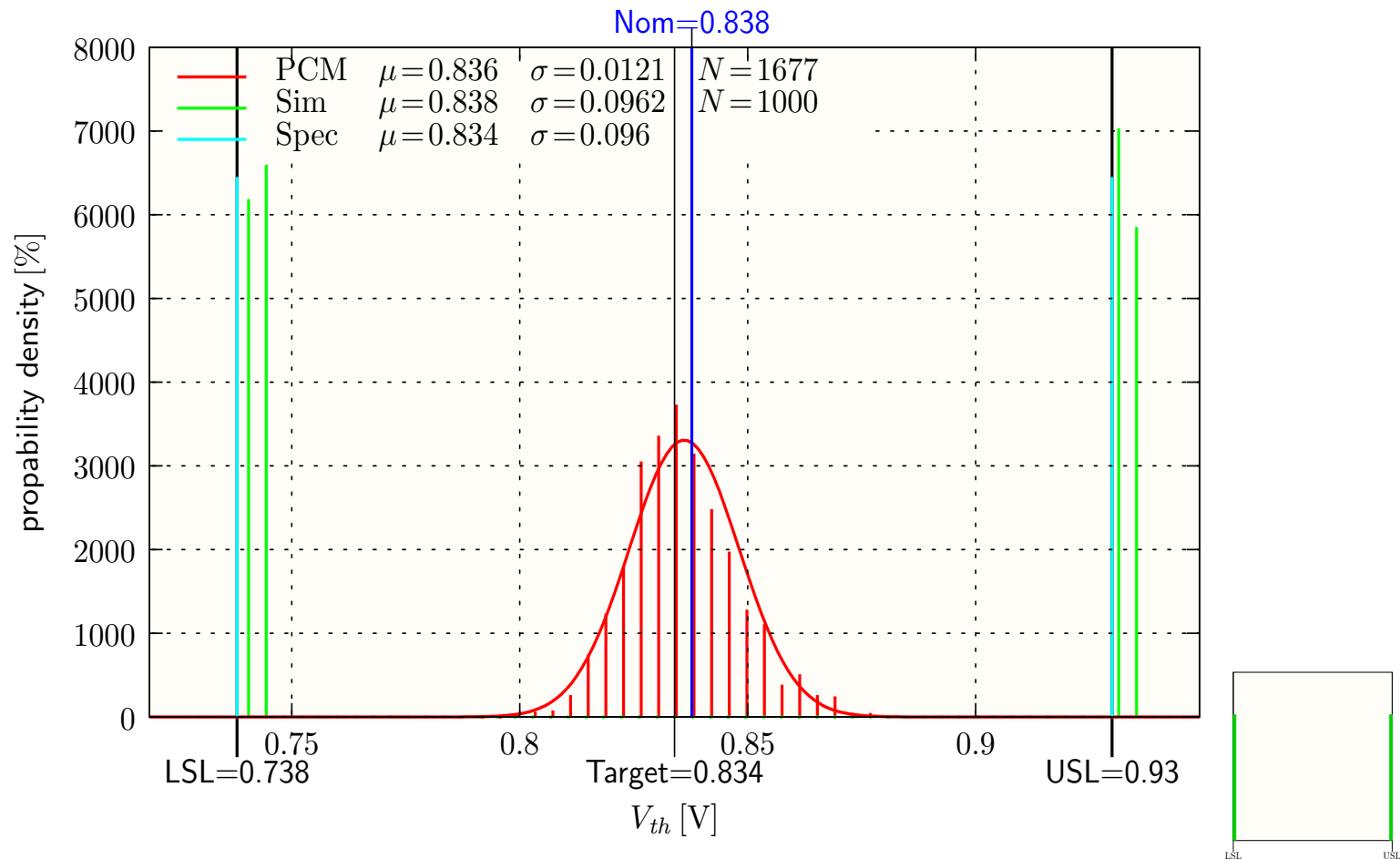
# Example 2: PCM Par $V_{t\_MNLE2}$ – MC Section *unif*



# Example 3: PCM Par $V_{t\_MNLE2}$ – MC Section *unif2s3s*



# Example 4: PCM Par $V_{t\_MNLE2}$ – MC Section *specLimits*



# Corner Sections



		Comment
<b>depFast_dmosFast</b>	<b>depSlow_dmosFast</b>	depFast: $\delta V_{th}(MNND) = -0.139V$ $\delta V_{th}(MNND2) = -0.154V$ dmosFast: $\delta I_{cap}(MNTE, MNSE2) = -0.25\mu m$
<b>depFast_dmosSlow</b>	<b>depSlow_dmosSlow</b>	depSlow: $\delta V_{th}(MNND, MNND2) = 0.243V$ dmosSlow: $\delta I_{cap}(MNTE, MNSE2) = 0.32\mu m$

There are no universally valid “worst cases” in BCD Technologies  
 → Corners have to be defined by Device Team  
 according to the needs of Product Development!

# Corner Sections



		Comment
<b>depFast_dmosFast</b>	<b>depSlow_dmosFast</b>	depFast: $\delta V_{th}(MNND) = -0.139V$ $\delta V_{th}(MNND2) = -0.154V$ dmosFast: $\delta l_{cap}(MNTE, MNSE2) = -0.25\mu m$
<b>depFast_dmosSlow</b>	<b>depSlow_dmosSlow</b>	depSlow: $\delta V_{th}(MNND, MNND2) = 0.243V$ dmosSlow: $\delta l_{cap}(MNTE, MNSE2) = 0.32\mu m$
<b>FastFast</b>	<b>SlowFast</b>	FastFast: $\delta V_{th}(NMOS) = -3\sigma$ $\delta V_{th}(PMOS) = 3\sigma$ $\delta t_{ox} = -3\sigma$ $\delta l_{int} = -3\sigma$ $\delta w_{int} = +3\sigma$ $\delta C_j = -3\sigma$ SlowFast: $\delta V_{th}(NMOS) = 3\sigma$ $\delta V_{th}(PMOS) = 3\sigma$
<b>FastSlow</b>	<b>SlowSlow</b>	SlowSlow: $\delta V_{th}(NMOS) = 3\sigma$ $\delta V_{th}(PMOS) = -3\sigma$ $\delta t_{ox} = +3\sigma$ $\delta l_{int} = +3\sigma$ $\delta w_{int} = -3\sigma$ $\delta C_j = +3\sigma$ FastSlow: $\delta V_{th}(NMOS) = -3\sigma$ $\delta V_{th}(PMOS) = -3\sigma$

# Model Sections

- 8 Monte Carlo Sections
  - 4 sections with different distributions
  - 4 "no Parasitics" sections (noPar) with neglect of:
    - (substrate) parasitic devices
    - voltage/current/power warnings
    - paramTests (geometry checks)
  - Corresponding *noPar* sections speed up simulation by  $\geq 25\%$ .
  - No section toggle required for nominal and Gaussian MC simulation
- 8 Corner Sections
  - 4 corners for NMOS/PMOS speed
  - 4 corners for leakage current of depletion MOS and slew rate of DMOS
  - Performing Monte Carlo analysis issues an error.



- The SMART5 PCM comprises 194 measurements (ASM52).
- 143 of them can be re-simulated.
- PCM evaluations may serve as a **testbench** to quantify the **model quality** (w/o correlation and mismatch).
  1. Does the nominal simulation reproduce the PCM Target?  
**nom = Target**
  2. Does the mean value of the Monte Carlo simulation reproduce the nominal value?  
 **$\mu = \text{nom}$**
  3. Does the standard deviation of the Monte Carlo simulation reproduce one third of the distance between the PCM Upper Spec Limit and the PCM Target (cpk=1)?  
 **$3 \sigma = \text{USL-Target}$**

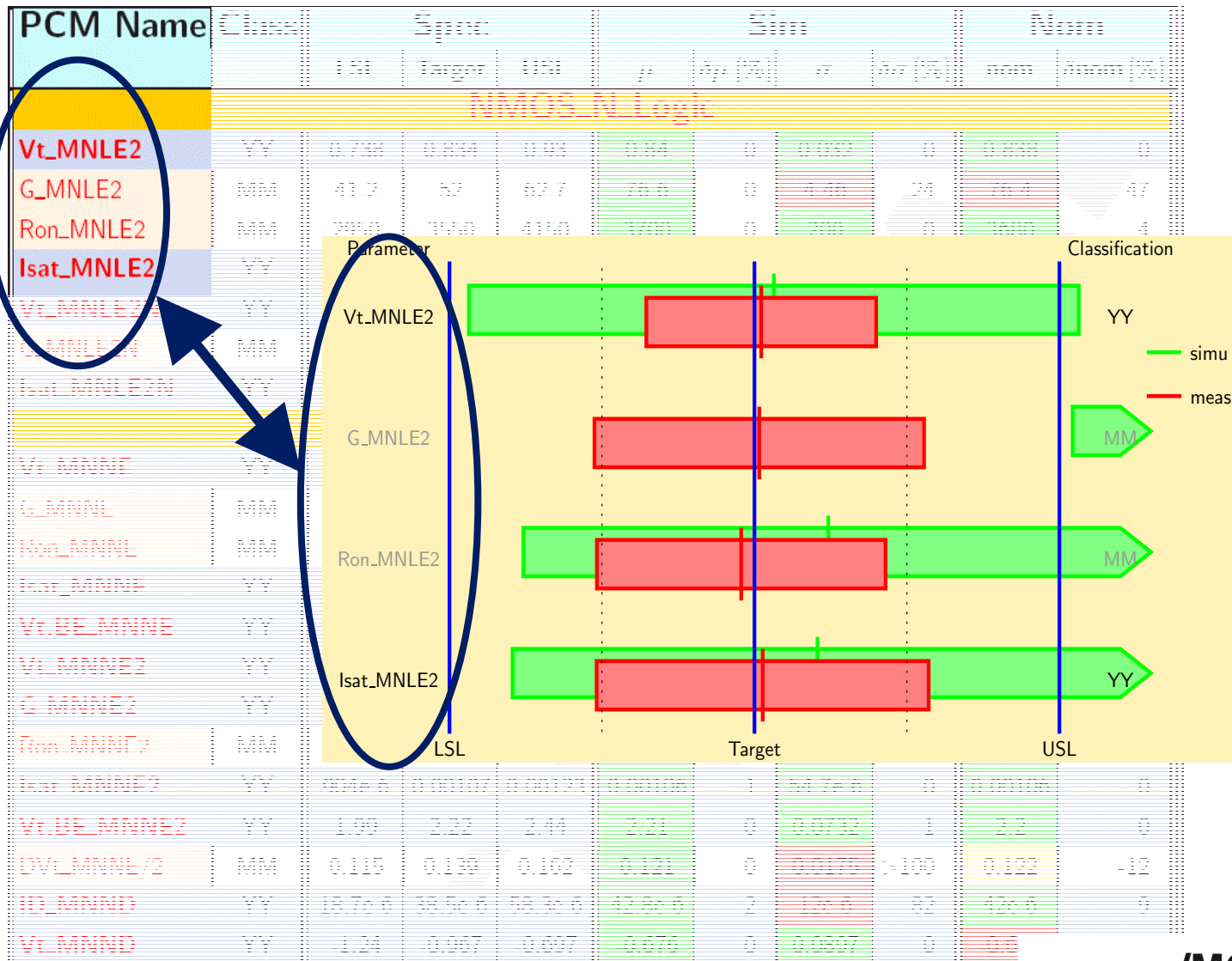
# Model Quality



PCM Name	Class	Spec			Sim				Nom	
		LSL	Target	USL	$\mu$	$\delta\mu$ [%]	$\sigma$	$\delta\sigma$ [%]	nom	$\delta\text{nom}$ [%]
<b>NMOS_N_Logic</b>										
Vt_MNLE2	YY	0.738	0.834	0.93	0.84	0	0.032	0	0.838	0
G_MNLE2	MM	41.2	52	62.7	76.6	0	4.46	24	76.4	47
Ron_MNLE2	MM	2950	3550	4150	3700	0	200	0	3680	4
Isat_MNLE2	YY	250e-6	306e-6	361e-6	317e-6	-1	18.5e-6	0	320e-6	5
Vt_MNLE2N	YY	0.738	0.834	0.931	0.84	0	0.0321	0	0.838	0
G_MNLE2N	MM	44	55.4	66.7	76.5	0	4.5	19	76.4	38
Isat_MNLE2N	YY	267e-6	321e-6	376e-6	319e-6	0	18.1e-6	0	320e-6	0
<b>NMOS_N_Low</b>										
Vt_MNNE	YY	0.905	0.994	1.08	0.985	0	0.0297	0	0.985	-1
G_MNNE	MM	79	91.1	103	119	0	4.66	15	118	30
Ron_MNNE	MM	1580	1770	1960	1730	0	63.4	0	1730	-2
Isat_MNNE	YY	835e-6	966e-6	0.0011	986e-6	-1	43.8e-6	0	992e-6	3
Vt_BE_MNNE	YY	2.3	2.5	2.71	2.48	0	0.0715	4	2.48	-1
Vt_MNNE2	YY	0.761	0.852	0.943	0.864	0	0.0304	0	0.863	1
G_MNNE2	YY	83.6	99.1	115	129	0	5.84	14	130	31
Ron_MNNE2	MM	1470	1690	1900	1650	0	71	0	1650	-2
Isat_MNNE2	YY	904e-6	0.00107	0.00123	0.00106	-1	54.7e-6	0	0.00106	0
Vt_BE_MNNE2	YY	1.99	2.22	2.44	2.21	0	0.0732	-1	2.2	0
DVt_MNNE/2	MM	0.115	0.139	0.162	0.121	0	0.0175	>100	0.122	-12
ID_MNND	YY	18.7e-6	38.5e-6	58.3e-6	42.8e-6	2	12e-6	82	42e-6	9
Vt_MNND	YY	-1.24	-0.967	-0.697	-0.676	0	0.0897	0	-0	

source: /MQ-Docu

# Model Quality



source: /MQ-Docu

# Conclusion

- PCM: not only Process Monitoring (TD), but also Device Monitoring (CAD)
- Recommended Usage of
  - Monte Carlo Section **nom** with  $\geq 100$  runs for small circuits
  - Monte Carlo Section **unif2s3s\_noPar** with  $\leq 100$  runs for large circuits
  - Corner Sections only if you know what you are doing (worst-worst case)
- Reproduction of Correlations
  - 😊 Monte Carlo Section **nom**
  - 😐 Monte Carlo Section **unif, unif2s3s, specLimits**
  - 😞 Corner Sections
- To be discussed
  - Benefits of Quarterly Monitoring?
  - Device type coverage (SMART5 PCM: 41 of 75 types)?
  - PCM measuring regions?
  - PCM AC and Temp measurements needed?